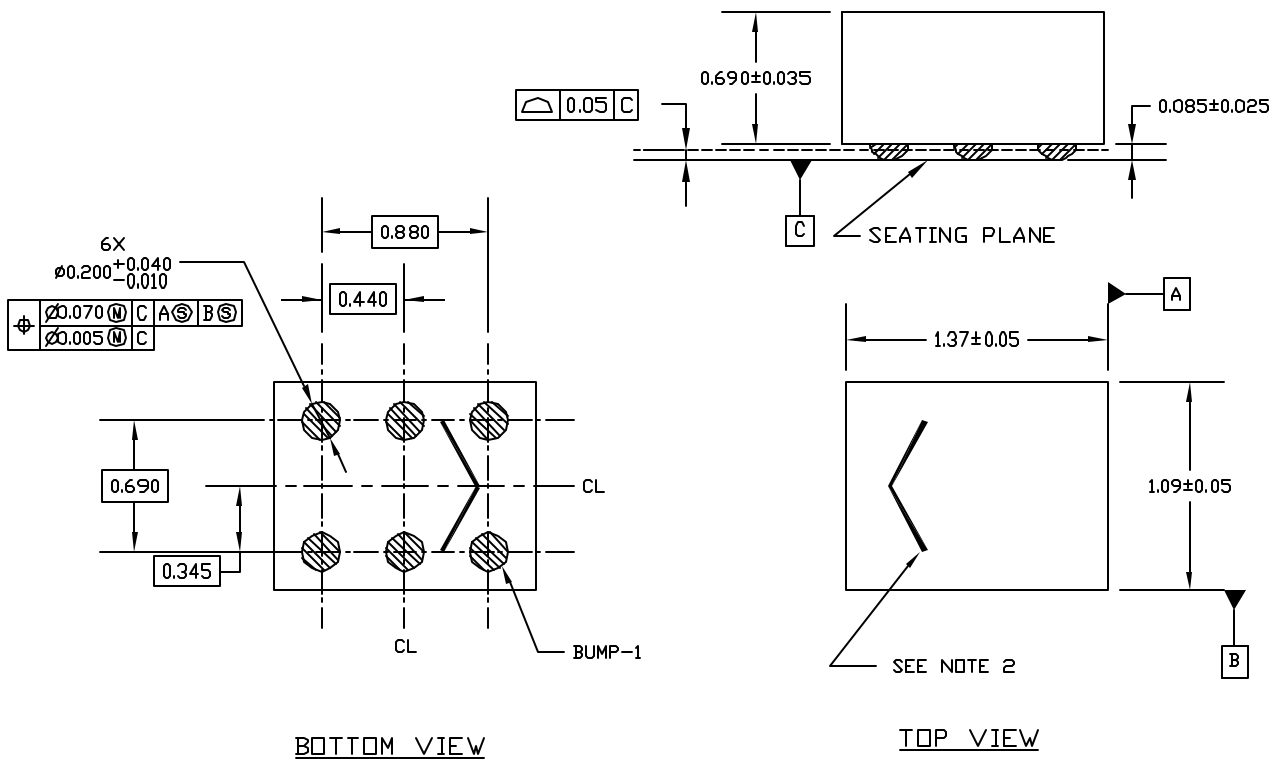


REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE		



BOTTOM VIEW

TOP VIEW

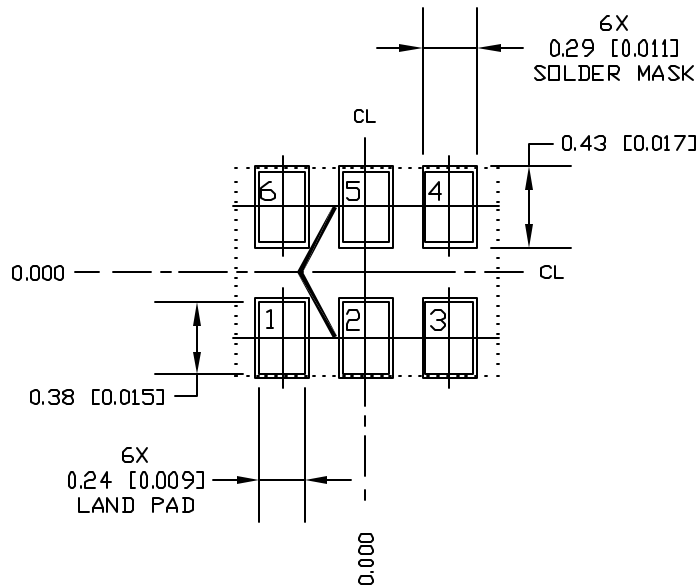
PACKAGE OUTLINE

SIGNATURE		DATE					
QA APVD:							
ENGR MGR:				DS2415X FLIP CHIP PACKAGE PACKAGE CODE: BF611-1			
ENGR BY: S. CHINNUSAMY 11/2006							
CHECK BY:				SIZE	FSCM NO.	DWG NO.	REV
DRAWN BY: B. MCCARTY 2/19/1999				A		56-G7017-001	A
SCALE				NONE		SHEET 1 / 2	

NOTES:

1. DIMENSIONS: MM [INCH]
2. LASER MARK
3. LANDING PAD NOT DEFINED BY SOLDER MASK; FOR PAD CONNECTIONS AND COORDINATES, SEE TABLE 1
4. UNDERFILL RECOMMENDED FOR FR4 SUBSTRATE APPLICATION

TABLE 1. LAND PAD CONNECTIONS AND CENTER COORDINATES						
NUMBER	NAME	MILLIMETERS		INCHES		
		X	Y	X	Y	
1	VSS	-0.440	-0.345	-0.0173	-0.0136	
2	IQ	0.000	-0.345	0.0000	-0.0136	
3	VDD	0.440	-0.345	0.0173	-0.0136	
4	VBATO	0.440	0.345	0.0173	0.0136	
5	X1	0.000	0.345	0.0000	0.0136	
6	X2	-0.440	0.345	-0.0173	0.0136	



TOP VIEW
PADS NUMBERED COUNTERCLOCKWISE
IN THIS VIEW

RECOMMENDED SUBSTRATE
LAND PATTERN

SIZE A	FSCM NO.	DWG NO. 56-G7017-001	REV B
SCALE	NONE	SHEET	2 / 2